PCN Number:		202	20220309004.1					PC	N Date:	May 11	L, 20)22
Title:	Title: Add Cu as Alternative Wire Base Metal for Selected Device(s)											
Customer Contact: PCN Manager Dept: Quality Services												
Proposed 1 st Ship Date:			Aug 11, 2022			Sample requests ac			epted until:	June 10), 202	22
*Sample requests received after (June 10, 2022) will not be supported.												
Change Type												
Assembly Site						sign			Wafer Bump Site			
Assembly Process						ta Sheet		1 4	Wafer Bump Material			
Assembly Materials			Part number change			+ $+$ $+$	Wafer Bump Process					
Mechanical Specification			Test Site				+H	Wafer Fab	b Site b Materials			
Packing/Shipping/Labeling			Test Process			╁∺						
PCN Details Wafer Fab Process												
Description of Change:												
Texas Instruments is pleased to announce the qualification of new assembly material set to add Cu as an additional bond wire option for devices listed in "Product affected" section below. Devices will remain in current assembly facility and piece part changes as follows:												
Material			Current			Proposed						
Wire type					6 mil				.00 mil Cu			
Reason for 0	Change:											
Continuity of												
,	ith world techn	ology ti	rends	and i	ISE W	virina with e	enhanced	l me	chanical and			
electrical		ology ci	i Ciias i	aria c	15C V	withing with t			criamical and			
	•	. Our Ac	scombl	lv/To	ct nr	adustian sit	-00					
	flexibility withir		sembi	iy/ i e	st þi	oduction Si	les.					
	er to obtain and impact on Fit,		Eumoi	tion	0	ditu or Dol	liability	(nos	itivo / nogat	hive \		
-	impact on Fit,	roi iii,	ruiic	tion,	Qua	ility of Kei	іаріпцу	(pos	itive / negat	live):		
None.												
Impact on E	nvironmental	Rating	JS									
	es indicate the sare checked, the									his chan	ge. I	[f
RoHS			REACH			Green Status		S	IEC 62	2474		
		⊠ No	Change			⊠ No C	hange		No Chan	ge		
Changes to product identification resulting from this PCN:												
None.												
Product Affected:												
TPS62172D9	[562172	DSGT									
L 11 3021/2D3		JUZI/Z	וטכעו									

Qualification Report

Approve Date 6-May-2022

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Туре	Test Name / Condition	Duration	Qual Device: TPS62172DSGR	QBS Product Reference: TPS62172DSGR	QBS Product Reference: TPS62160DSGR	QBS Package Reference: <u>TPS65680RSN</u>	QBS Process Reference: TPS62110RSA
ED	Electrical Characterization	Per Datasheet Parameters	-	Pass	Pass	Pass	Pass
HBM	ESD - HBM	3000 V	•	-	1/3/0	2/6/0	-
CDM	ESD - CDM	1500 V	-	-	1/3/0	2/6/0	-
LU	Latch-up	(Per JESD78)	-	-	1/6/0	2/12/0	3/15/0
HTOL	Life Test, 150C	300 Hours	-	-	-	3/231/0	-
HTOL	Life Test, 140C	480 Hours	-	-	-	-	3/231/0
HTOL	Life Test, 125C	1000 Hours	-	-	-	-	-
ELFR	Early Life Failure Rate, 140C	48 Hours	-	-	-	-	3/1881/0
HTSL	High Temp Storage Bake, 170C	420 Hours	-	-	-	2/154/0	3/231/0
HTSL	High Temp Storage Bake, 150C	1000 Hours		-	-	1/77/0	-
HAST	Biased HAST, 130C/85%RH	96 Hours	-	-	-	3/231/0	3/231/0
UHAST	Unbiased HAST, 130C/85%RH	96 Hours	-	-	-	3/231/0	-
AC	Autoclave 121C	96 Hours	-	-	-	-	3/231/0
TC	Temperature Cycle, -65/150C	500 Cycles	-	-	-	3/231/0	-
TC	Temperature Cycle, -55/125C	700 Cycles	-	-	-	-	3/231/0
FTY	Final Test Yield	-	Pass	-	-	-	-
MQ	Manufacturability (Assembly)	(per mfg. Site specification)	Pass	Pass	-	-	-

- QBS: Qual By Similarity
- Qual Device TPS62172DSGR is qualified at MSL2 260C
- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of $0.7 \mathrm{eV}$: $150 \mathrm{C}/1 \mathrm{k}$ Hours, and $170 \mathrm{C}/420$ Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles Quality and Environmental data is available at TI's external Web site: http://www.ti.com/Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail				
WW PCN Team	PCN www admin_team@list.ti.com				

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